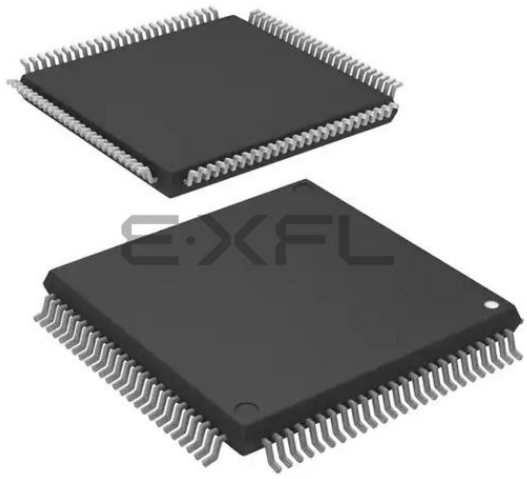
Renesas Electronics America Inc - M30302FCPGP#U5 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	M16C/60
Core Size	16-Bit
Speed	16MHz
Connectivity	I²C, IEBus, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	5K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 18x10b
Oscillator Type	External
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30302fcpgp-u5

1.4 Product List

Table 1.2 lists the M16C/30P group products and Figure 1.2 shows the Part No., Memory Size, and Package. Table 1.4 lists Product Code of MASK ROM version for M16C/30P. Figure 1.3 shows the Marking Diagram of Mask ROM Version for M16C/30P (Top View). Table 1.5 lists Product Code of One Time Flash version, Flash Memory version, and ROM-less version for M16C/30P. Figure 1.4 shows the Marking Diagram of One Time Flash version, Flash Memory version, and ROM-less Version for M16C/30P (Top View). Please specify the marking for M16C30P (MASK ROM version) when placing an order for ROM.

Table 1.2 Product List (1) **As of March 2007**

Part No.	ROM Capacity	RAM Capacity	package code (1)	Remarks
M30302MAP-XXXFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	Mask ROM version
M30302MAP-XXXGP			PLQP0100KB-A	
M30302MCP-XXXFP	128 Kbytes		PRQP0100JB-A	
M30302MCP-XXXGP			PLQP0100KB-A	
M30302MDP-XXXFP	160 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302MDP-XXXGP			PLQP0100KB-A	
M30302MEP-XXXFP	192 Kbytes		PRQP0100JB-A	
M30302MEP-XXXGP			PLQP0100KB-A	
M30302GAPFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	One Time Flash version (blank product)
M30302GAPGP (D)			PLQP0100KB-A	
M30302GCPFP	128 Kbytes		PRQP0100JB-A	
M30302GCPGP (D)			PLQP0100KB-A	
M30302GDPFP	160 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GDPGP (D)			PLQP0100KB-A	
M30304GDPFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GDPGP (D)			PLQP0100KB-A	
M30302GEPFP	192 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GEPGP (D)			PLQP0100KB-A	
M30304GEPFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GEPGP (D)			PLQP0100KB-A	
M30302GGPFP (D)	256 Kbytes	12 Kbytes	PRQP0100JB-A	
M30302GGPGP (D)			PLQP0100KB-A	
M30302GAP-XXXFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	One Time Flash version (factory programmed product)
M30302GAPvGP (D)			PLQP0100KB-A	
M30302GCP-XXXFP	128 Kbytes		PRQP0100JB-A	
M30302GCP-XXXGP (D)			PLQP0100KB-A	
M30302GDP-XXXFP	160 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GDP-XXXGP (D)			PLQP0100KB-A	
M30304GDP-XXXFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GDP-XXXGP (D)			PLQP0100KB-A	
M30302GEP-XXXFP	192 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GEP-XXXGP (D)			PLQP0100KB-A	
M30304GEP-XXXFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GEP-XXXGP (D)			PLQP0100KB-A	
M30302GGP-XXXFP (D)	256 Kbytes	12 Kbytes	PRQP0100JB-A	
M30302GGP-XXXGP (D)			PLQP0100KB-A	

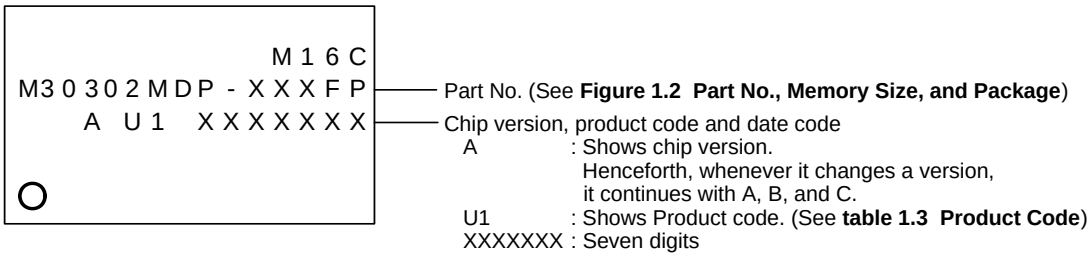
(D): Under development
(P): Under planning
NOTES:
1. Previous package codes are as follows.
   PRQP0100JB-A : 100P6S-A,
   PLQP0100KB-A : 100P6Q-A
2. Block A (4-Kbytes space) is available in flash memory version.

Table 1.4 Product Code of MASK ROM version for M16C/30P

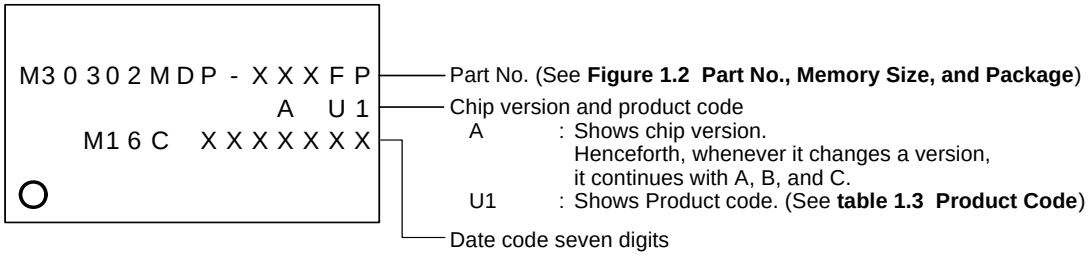
Product Code	Package	Operating Ambient Temperature
U1	Lead-free	-20°C to 85°C
U4		-40°C to 85°C

PRQP0100JB-A (100P6S-A)

1. Standard Renesas Mark

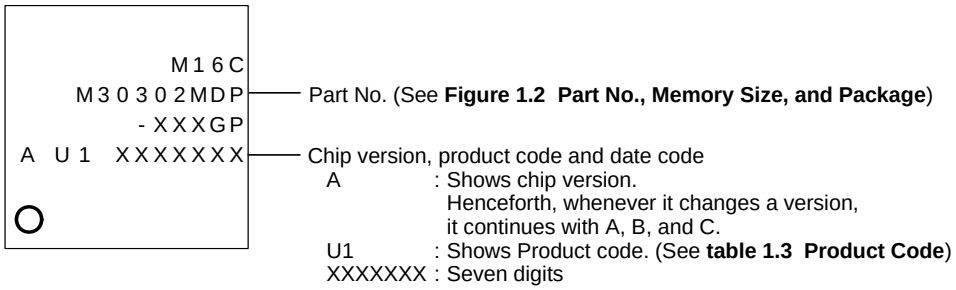


2. Customer's Parts Number + Renesas catalog name

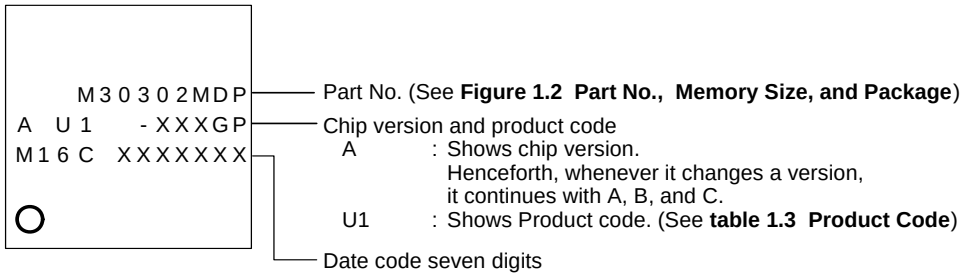


PLQP0100KB-A (100P6Q-A)

1. Standard Renesas Mark



2. Customer's Parts Number + Renesas catalog name



NOTES:
1. Refer to the **mark specification form** for details of the Mask ROM version marking.

Figure 1.3 Marking Diagram of Mask ROM Version for M16C/30P (Top View)

1.5 Pin Configuration

Figures 1.5 to 1.6 show the pin configurations (top view).

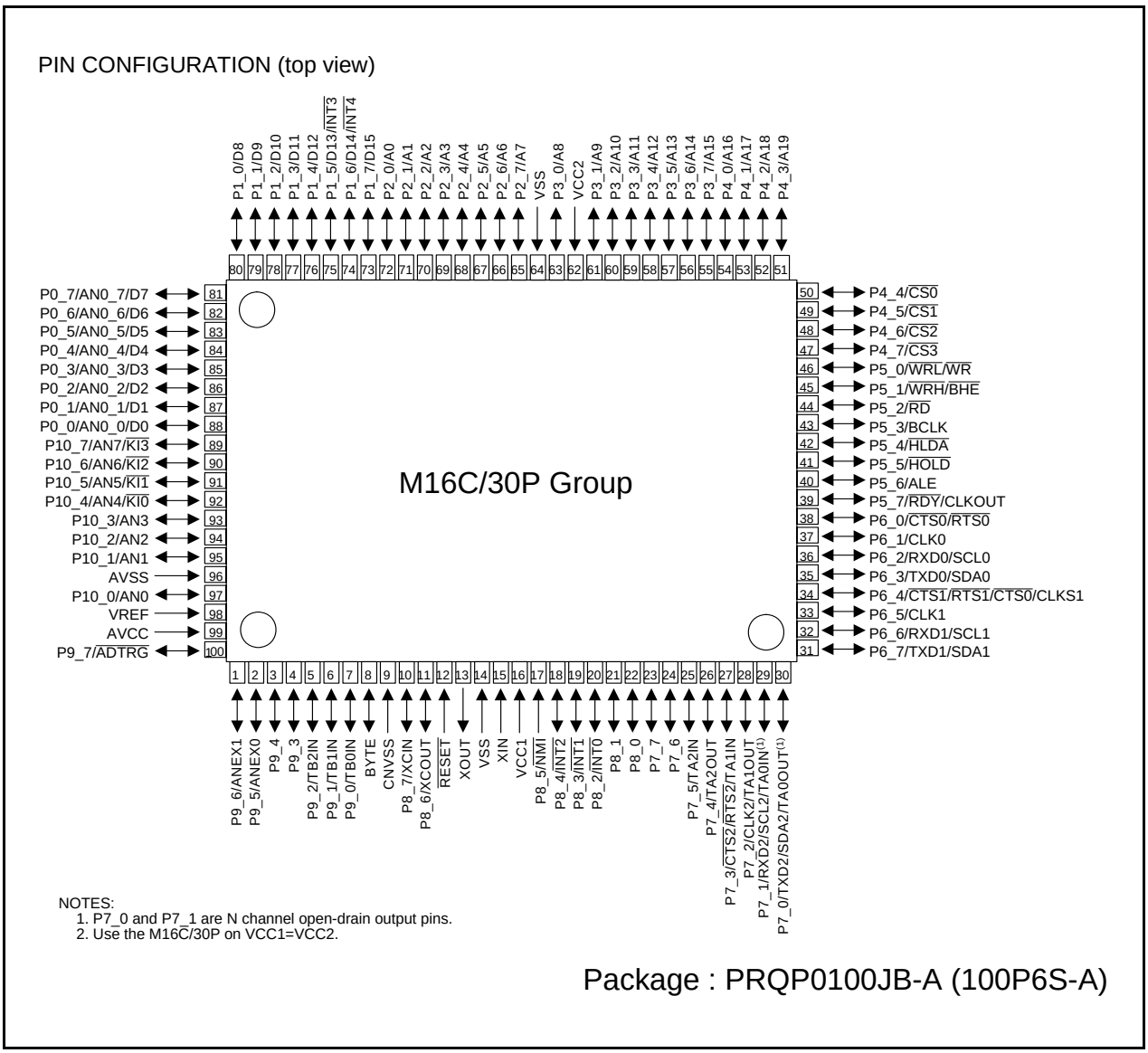
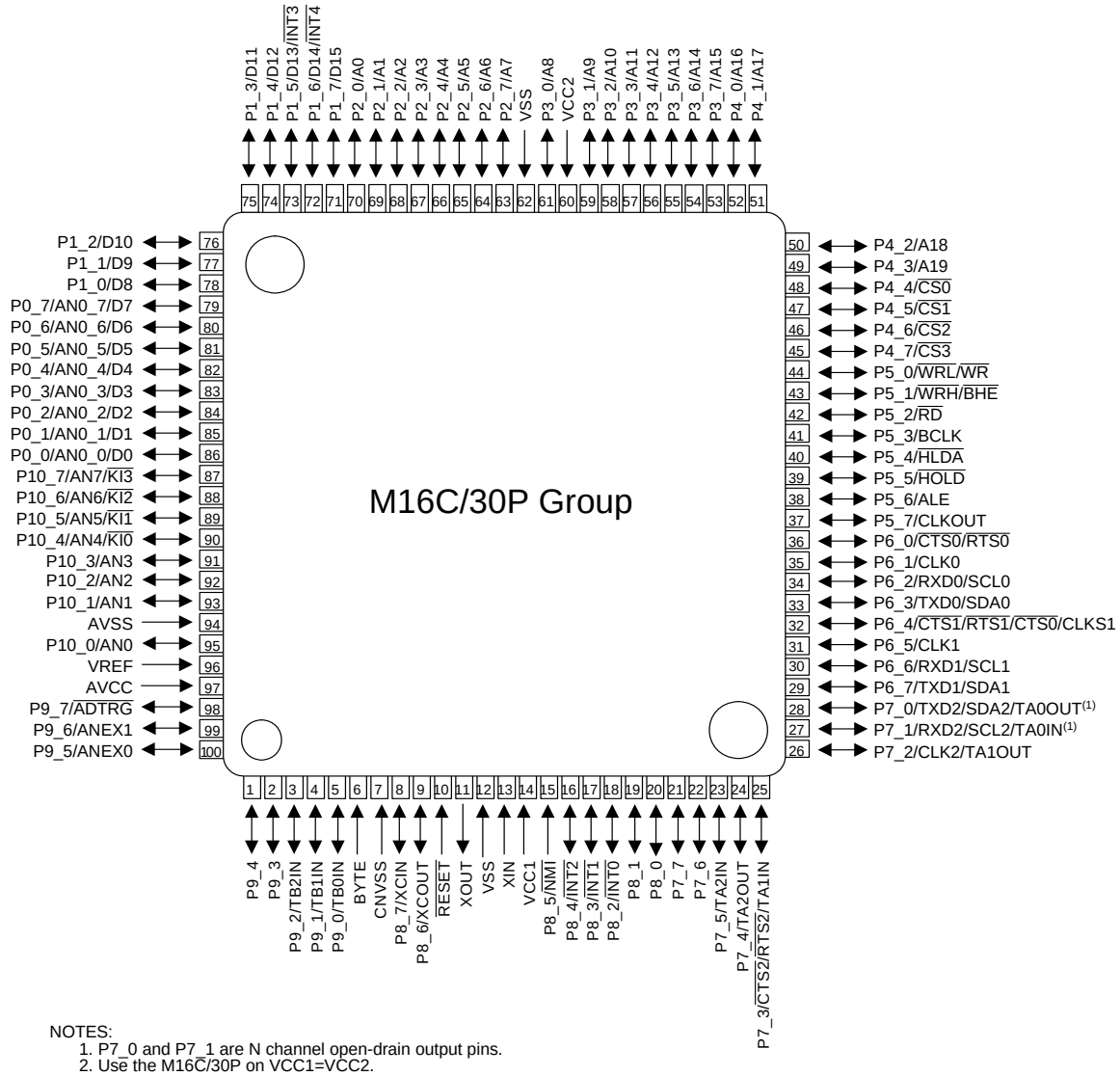


Figure 1.5 Pin Configuration (Top View)

PIN CONFIGURATION (top view)



NOTES:
1. P7_0 and P7_1 are N channel open-drain output pins.
2. Use the M16C/30P on VCC1=VCC2.

Package : PLQP0100KB-A (100P6Q-A)

Figure 1.6 Pin Configuration (Top View)

Table 1.6 Pin Characteristics (1)

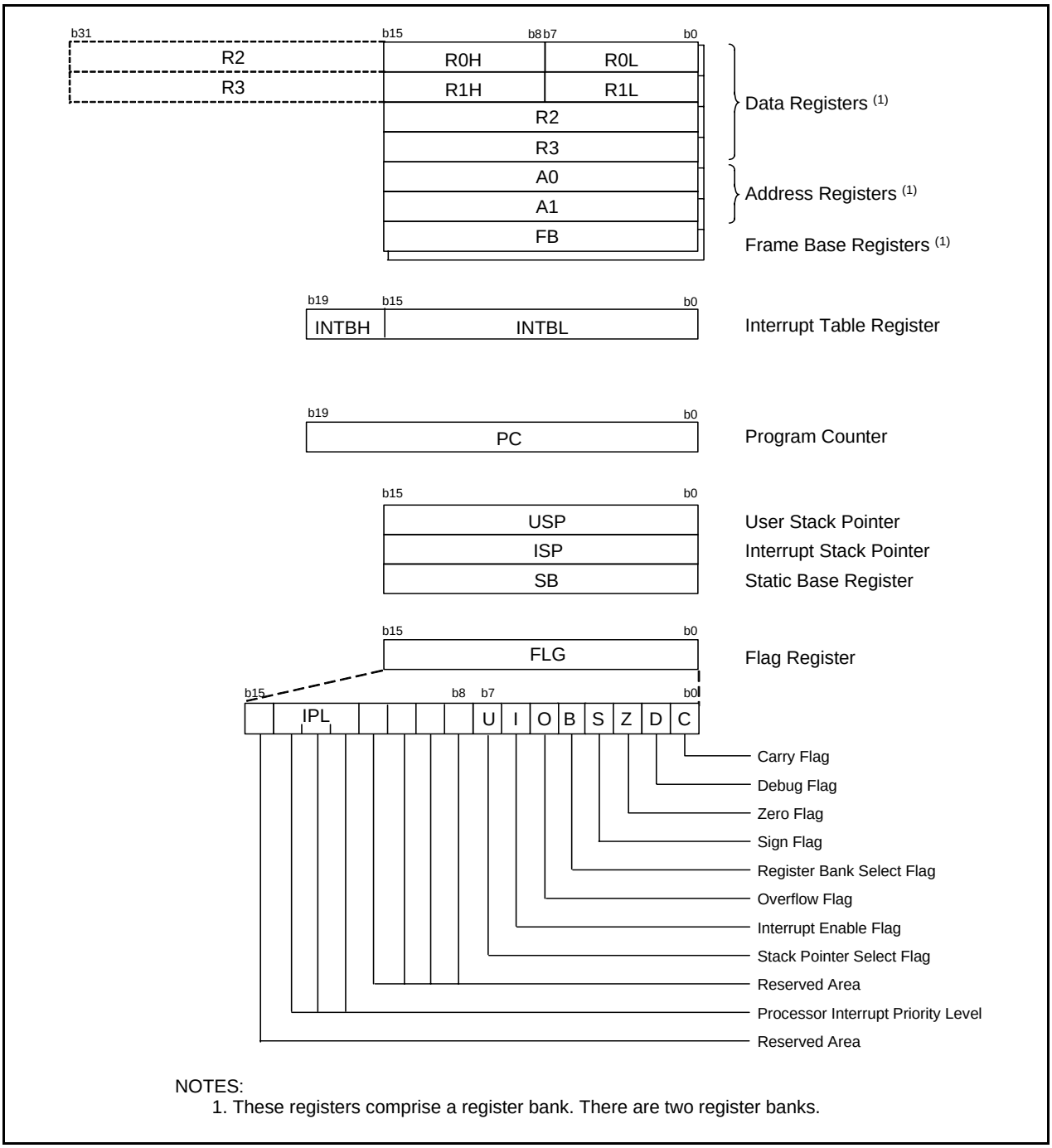
Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
FP	GP							
1	99		P9_6				ANEX1	
2	100		P9_5				ANEX0	
3	1		P9_4					
4	2		P9_3					
5	3		P9_2		TB2IN			
6	4		P9_1		TB1IN			
7	5		P9_0		TB0IN			
8	6	BYTE						
9	7	CNVSS						
10	8	XCIN	P8_7					
11	9	XCOUT	P8_6					
12	10	$\overline{\text{RESET}}$						
13	11	XOUT						
14	12	VSS						
15	13	XIN						
16	14	VCC1						
17	15		P8_5	$\overline{\text{NMI}}$				
18	16		P8_4	$\overline{\text{INT2}}$				
19	17		P8_3	$\overline{\text{INT1}}$				
20	18		P8_2	$\overline{\text{INT0}}$				
21	19		P8_1					
22	20		P8_0					
23	21		P7_7					
24	22		P7_6					
25	23		P7_5		TA2IN			
26	24		P7_4		TA2OUT			
27	25		P7_3		TA1IN	$\overline{\text{CTS2}}/\overline{\text{RTS2}}$		
28	26		P7_2		TA1OUT	CLK2		
29	27		P7_1		TA0IN	RXD2/SCL2		
30	28		P7_0		TA0OUT	TXD2/SDA2		
31	29		P6_7			TXD1/SDA1		
32	30		P6_6			RXD1/SCL1		
33	31		P6_5			CLK1		
34	32		P6_4			$\overline{\text{CTS1}}/\overline{\text{RTS1}}/\overline{\text{CTS0}}$/CLKS1		
35	33		P6_3			TXD0/SDA0		
36	34		P6_2			RXD0/SCL0		
37	35		P6_1			CLK0		
38	36		P6_0			$\overline{\text{CTS0}}/\overline{\text{RTS0}}$		
39	37		P5_7					$\overline{\text{RDY}}$/CLKOUT
40	38		P5_6					ALE
41	39		P5_5					$\overline{\text{HOLD}}$
42	40		P5_4					$\overline{\text{HLDA}}$
43	41		P5_3					BCLK
44	42		P5_2					$\overline{\text{RD}}$
45	43		P5_1					$\overline{\text{WRH}}/\overline{\text{BHE}}$
46	44		P5_0					$\overline{\text{WRL}}/\overline{\text{WR}}$
47	45		P4_7					$\overline{\text{CS3}}$
48	46		P4_6					$\overline{\text{CS2}}$
49	47		P4_5					$\overline{\text{CS1}}$
50	48		P4_4					$\overline{\text{CS0}}$

Table 1.7 Pin Characteristics (2)

Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
FP	GP							
51	49		P4_3					A19
52	50		P4_2					A18
53	51		P4_1					A17
54	52		P4_0					A16
55	53		P3_7					A15
56	54		P3_6					A14
57	55		P3_5					A13
58	56		P3_4					A12
59	57		P3_3					A11
60	58		P3_2					A10
61	59		P3_1					A9
62	60	VCC2						
63	61		P3_0					A8
64	62	VSS						
65	63		P2_7					A7
66	64		P2_6					A6
67	65		P2_5					A5
68	66		P2_4					A4
69	67		P2_3					A3
70	68		P2_2					A2
71	69		P2_1					A1
72	70		P2_0					A0
73	71		P1_7					D15
74	72		P1_6	$\overline{\text{INT4}}$				D14
75	73		P1_5	$\overline{\text{INT3}}$				D13
76	74		P1_4					D12
77	75		P1_3					D11
78	76		P1_2					D10
79	77		P1_1					D9
80	78		P1_0					D8
81	79		P0_7				AN0_7	D7
82	80		P0_6				AN0_6	D6
83	81		P0_5				AN0_5	D5
84	82		P0_4				AN0_4	D4
85	83		P0_3				AN0_3	D3
86	84		P0_2				AN0_2	D2
87	85		P0_1				AN0_1	D1
88	86		P0_0				AN0_0	D0
89	87		P10_7	$\overline{\text{KI3}}$			AN7	
90	88		P10_6	$\overline{\text{KI2}}$			AN6	
91	89		P10_5	$\overline{\text{KI1}}$			AN5	
92	90		P10_4	$\overline{\text{KI0}}$			AN4	
93	91		P10_3				AN3	
94	92		P10_2				AN2	
95	93		P10_1				AN1	
96	94	AVSS						
97	95		P10_0				AN0	
98	96	VREF						
99	97	AVCC						
100	98		P9_7				$\overline{\text{ADTRG}}$	

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers. The CPU has 13 registers. Of these, R0, R1, R2, R3, A0, A1 and FB comprise a register bank. There are two register banks.



NOTES:
1. These registers comprise a register bank. There are two register banks.

Figure 2.1 Central Processing Unit Register

2.1 Data Registers (R0, R1, R2 and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers.

R1H and R1L are the same as R0H and R0L. Conversely, R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is the same as R2R0.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is “0”; USP is selected when the U flag is “1”.
The U flag is cleared to “0” when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

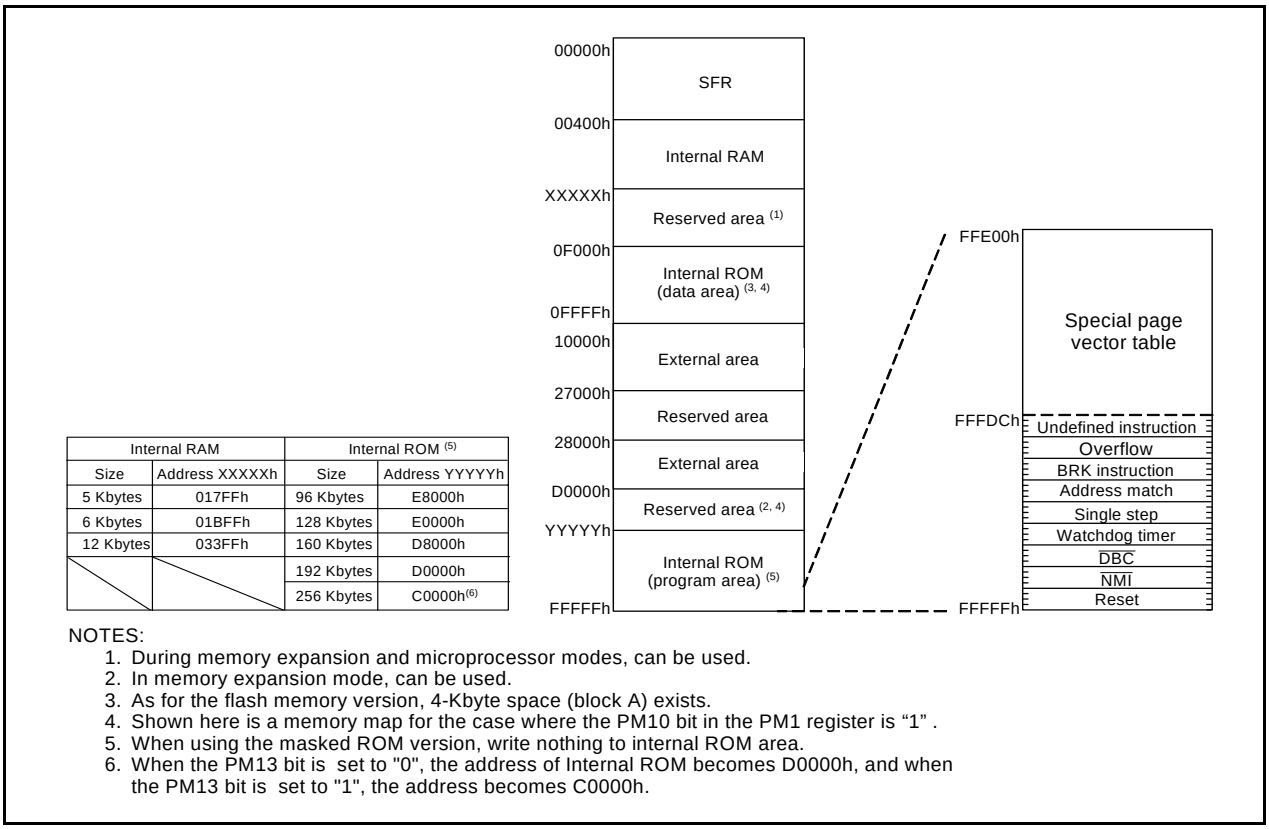
IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has priority greater than IPL, the interrupt is enabled.

2.8.10 Reserved Area

When write to this bit, write “0”. When read, its content is indeterminate.

3. Memory

Figure 3.1 is a Memory Map of the M16C/30P group. The address space extends the 1 Mbyte from address 00000h to FFFFFh.
The internal ROM is allocated in a lower address direction beginning with address FFFFFh. For example, a 64-Kbyte internal ROM is allocated to the addresses from F0000h to FFFFFh.
The fixed interrupt vector table is allocated to the addresses from FFFDCh to FFFFFh. Therefore, store the start address of each interrupt routine here.
The internal RAM is allocated in an upper address direction beginning with address 00400h. For example, a 5-Kbyte internal RAM is allocated to the addresses from 00400h to 017FFh. In addition to storing data, the internal RAM also stores the stack used when calling subroutines and when interrupts are generated. The SFR is allocated to the addresses from 00000h to 003FFh. Peripheral function control registers are located here. Of the SFR, any area which has no functions allocated is reserved for future use and cannot be used by users.
The special page vector table is allocated to the addresses from FFE00h to FFFDBh. This vector is used by the JMPS or JSRS instruction. For details, refer to the **M16C/60 and M16C/20 Series Software Manual**.



Internal RAM		Internal ROM (5)	
Size	Address XXXXXh	Size	Address YYYYYh
5 Kbytes	017FFh	96 Kbytes	E8000h
6 Kbytes	01BFFh	128 Kbytes	E0000h
12 Kbytes	033FFh	160 Kbytes	D8000h
		192 Kbytes	D0000h
		256 Kbytes	C0000h(6)

NOTES:
1. During memory expansion and microprocessor modes, can be used.
2. In memory expansion mode, can be used.
3. As for the flash memory version, 4-Kbyte space (block A) exists.
4. Shown here is a memory map for the case where the PM10 bit in the PM1 register is “1” .
5. When using the masked ROM version, write nothing to internal ROM area.
6. When the PM13 bit is set to "0", the address of Internal ROM becomes D0000h, and when the PM13 bit is set to "1", the address becomes C0000h.

Figure 3.1 Memory Map

Table 4.3 SFR Information (3) (1)

Address	Register	Symbol	After Reset
0340h			
0341h			
0342h			
0343h			
0344h			
0345h			
0346h			
0347h			
0348h			
0349h			
034Ah			
034Bh			
034Ch			
034Dh			
034Eh			
034Fh			
0350h			
0351h			
0352h			
0353h			
0354h			
0355h			
0356h			
0357h			
0358h			
0359h			
035Ah			
035Bh			
035Ch			
035Dh			
035Eh	Interrupt Factor Select Register 2	IFSR2A	00XXXXXXb
035Fh	Interrupt Factor Select Register	IFSR	00h
0360h			
0361h			
0362h			
0363h			
0364h			
0365h			
0366h			
0367h			
0368h			
0369h			
036Ah			
036Bh			
036Ch	UART0 Special Mode Register 4	U0SMR4	00h
036Dh	UART0 Special Mode Register 3	U0SMR3	000X0X0Xb
036Eh	UART0 Special Mode Register 2	U0SMR2	X0000000b
036Fh	UART0 Special Mode Register	U0SMR	X0000000b
0370h	UART1 Special Mode Register 4	U1SMR4	00h
0371h	UART1 Special Mode Register 3	U1SMR3	000X0X0Xb
0372h	UART1 Special Mode Register 2	U1SMR2	X0000000b
0373h	UART1 Special Mode Register	U1SMR	X0000000b
0374h	UART2 Special Mode Register 4	U2SMR4	00h
0375h	UART2 Special Mode Register 3	U2SMR3	000X0X0Xb
0376h	UART2 Special Mode Register 2	U2SMR2	X0000000b
0377h	UART2 Special Mode Register	U2SMR	X0000000b
0378h	UART2 Transmit/Receive Mode Register	U2MR	00h
0379h	UART2 Bit Rate Generator	U2BRG	XXh
037Ah 037Bh	UART2 Transmit Buffer Register	U2TB	XXh XXh
037Ch	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
037Dh	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
037Eh 037Fh	UART2 Receive Buffer Register	U2RB	XXh XXh

NOTES:
1. The blank areas are reserved and cannot be accessed by users.

X : Nothing is mapped to this bit

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC}	Supply Voltage(V_{CC1}=V_{CC2})		V_{CC1}=V_{CC2}=AVcc	–0.3 to 6.5	V
AVcc	Analog Supply Voltage		V_{CC1}=V_{CC2}=AVcc	–0.3 to 6.5	V
V_I	Input Voltage	$\overline{\text{RESET}}$, CNVSS, BYTE, P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, VREF, XIN		–0.3 to V_{CC}+0.3	V
		P7_0, P7_1		–0.3 to 6.5	V
V_O	Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, XOUT		–0.3 to V_{CC}+0.3	V
		P7_0, P7_1		–0.3 to 6.5	V
P_d	Power Dissipation		–40°C<T_{opr}≤85°C	300	mW
T_{opr}	Operating Ambient Temperature	When the Microcomputer is Operating		–20 to 85 / –40 to 85	°C
		One Time Flash Program Erase		0 to 60	
		Flash Program Erase		0 to 60	
T_{stg}	Storage Temperature			–65 to 150	°C

Table 5.10 Electrical Characteristics (2) (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power Supply Current (V_{CC1}=V_{CC2}=4.0V to 5.5V)	In single-chip mode, the output pins are open and other pins are V_{SS}	Mask ROM	f(XIN)=16MHz No division		10	15	mA
			One Time Flash	f(XIN)=16MHz, No division		10	18	mA
			Flash Memory	f(XIN)=16MHz, No division		12	18	mA
			One Time Flash	f(XIN)=10MHz, VCC1=5.0V		15		mA
			Flash Memory Program	f(XIN)=10MHz, VCC1=5.0V		15		mA
			Flash Memory Erase	f(XIN)=10MHz, VCC1=5.0V		25		mA
			Mask ROM	f(XCIN)=32kHz Low power dissipation mode, ROM (3)		25		µA
			One Time Flash	f(XCIN)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(XCIN)=32kHz Low power dissipation mode, Flash Memory (3)		350		µA
			Flash Memory	f(XCIN)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(XCIN)=32kHz Low power dissipation mode, Flash Memory (3)		420		µA
			Mask ROM One Time Flash Flash Memory	f(XCIN)=32kHz Wait mode (2), Oscillation capability High		7.5		µA
				f(XCIN)=32kHz Wait mode (2), Oscillation capability Low		2.0		µA
				Stop mode Topr =25°C		0.8	3.0	µA

NOTES:
1. Referenced to V_{CC1}=V_{CC2}=4.2 to 5.5V, V_{SS} = 0V at T_{opr} = –20 to 85°C / –40 to 85°C, f(XIN)=16MHz unless otherwise specified.
2. With one timer operated using fC32.
3. This indicates the memory in which the program to be executed exists.

$V_{CC1}=V_{CC2}=3V$

Table 5.27 Electrical Characteristics (1) (1)

Symbol	Parameter			Measuring Condition	Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	HIGH Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7		I_{OH}=–1mA	V_{CC}–0.5		V_{CC}	V
V_{OH}	HIGH Output Voltage XOUT		HIGHPOWER	I_{OH}=–0.1mA	V_{CC}–0.5		V_{CC}	V
			LOWPOWER	I_{OH}=–50µA	V_{CC}–0.5		V_{CC}	
	HIGH Output Voltage XCOUT		HIGHPOWER	With no load applied		2.5		V
			LOWPOWER	With no load applied		1.6		
V_{OL}	LOW Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7		I_{OL}=1mA			0.5	V
V_{OL}	LOW Output Voltage XOUT		HIGHPOWER	I_{OL}=0.1mA			0.5	V
			LOWPOWER	I_{OL}=50µA			0.5	
	LOW Output Voltage XCOUT		HIGHPOWER	With no load applied		0		V
			LOWPOWER	With no load applied		0		
V_{T+}-V_{T-}	Hysteresis	TA0IN to TA2IN, TB0IN to TB2IN, $\overline{INT0}$ to $\overline{INT4}$, $\overline{NMI}$, $\overline{ADTRG}$, $\overline{CTS0}$ to $\overline{CTS2}$, RXD0 to RXD2, CLK0 to CLK2, TA0OUT to TA2OUT, $\overline{KI0}$ to $\overline{KI3}$, SCL0 to SCL2, SDA0 to SDA2			0.2		0.8	V
V_{T+}-V_{T-}	Hysteresis	$\overline{RESET}$			0.2	(0.7)	1.8	V
I_{IH}	HIGH Input Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{RESET}$, CNVSS, BYTE		V_I=3V			4.0	µA
I_{IL}	LOW Input Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{RESET}$, CNVSS, BYTE		V_I=0V			–4.0	µA
R_{PULLUP}	Pull-Up Resistance	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7		V_I=0V	50	100	500	kΩ
R_{fXIN}	Feedback Resistance	XIN				3.0		MΩ
R_{fXCIN}	Feedback Resistance	XCIN				25		MΩ
V_{RAM}	RAM Retention Voltage			At stop mode	2.0			V

NOTES:
1. Referenced to V_{CC1} = V_{CC2} = 2.7 to 3.3V, V_{SS} = 0V at Topr = –20 to 85°C / –40 to 85°C, f(XIN)=10MHz no wait unless otherwise specified.

Table 5.28 Electrical Characteristics (2) (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power Supply Current (V_{CC1}=V_{CC2}=2.7V to 3.6V)	In single-chip mode, the output pins are open and other pins are V_{SS}	Mask ROM	f(XIN)=10MHz No division		8	11	mA
			One Time Flash	f(XIN)=10MHz, No division		8	13	mA
			Flash Memory	f(XIN)=10MHz, No division		8	13	mA
			Flash Memory Program	f(XIN)=10MHz, VCC1=3.0V		12		mA
			One Time Flash Program	f(XIN)=10MHz, VCC1=3.0V		12		mA
			Flash Memory Erase	f(XIN)=10MHz, VCC1=3.0V		22		mA
			Mask ROM	f(XCIN)=32kHz Low power dissipation mode, ROM (3)		25		µA
			One Time Flash	f(XCIN)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(XCIN)=32kHz Low power dissipation mode, Flash Memory (3)		350		µA
			Flash Memory	f(XCIN)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(XCIN)=32kHz Low power dissipation mode, Flash Memory (3)		420		µA
			Mask ROM One Time Flash Flash Memory	f(XCIN)=32kHz Wait mode (2), Oscillation capability High		6.0		µA
				f(XCIN)=32kHz Wait mode (2), Oscillation capability Low		1.8		µA
				Stop mode Topr =25°C		0.7	3.0	µA

NOTES:
1. Referenced to V_{CC1}=V_{CC2}=2.7 to 3.3V, V_{SS} = 0V at T_{opr} = –20 to 85°C / –40 to 85°C, f(XIN)=10MHz unless otherwise specified.
2. With one timer operated using fC32.
3. This indicates the memory in which the program to be executed exists.

$V_{CC1}=V_{CC2}=3V$

Timing Requirements

(V_{CC1} = V_{CC2} = 3V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.29 External Clock Input (XIN input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	(NOTE 2)		ns
$t_{w(H)}$	External Clock Input HIGH Pulse Width	(NOTE 3)		ns
$t_{w(L)}$	External Clock Input LOW Pulse Width	(NOTE 3)		ns
t_r	External Clock Rise Time		(NOTE 4)	ns
t_f	External Clock Fall Time		(NOTE 4)	ns

NOTES:

1. The condition is V_{CC1}=V_{CC2}=2.7 to 3.0V.
2. Calculated according to the V_{CC1} voltage as follows:

$$\frac{10^{-6}}{20 \times V_{CC1} - 44} \text{ [ns]}$$

3. Calculated according to the V_{CC1} voltage as follows:

$$\frac{10^{-6}}{20 \times V_{CC1} - 44} \times 0.4 \text{ [ns]}$$

4. Calculated according to the V_{CC1} voltage as follows:

$$-10 \times V_{CC1} + 45 \text{ [ns]}$$

Table 5.30 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data Input Access Time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data Input Access Time (for setting with wait)		(NOTE 2)	ns
$t_{su(DB-RD)}$	Data Input Setup Time	50		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ Input Setup Time	40		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ Input Setup Time	50		ns
$t_{h(RD-DB)}$	Data Input Hold Time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ Input Hold Time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ Input Hold Time	0		ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 60 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 60 \text{ [ns]}$$ n is "2" for 1-wait setting.

$V_{CC1}=V_{CC2}=3V$

Timing Requirements
(V_{CC1} = V_{CC2} = 3V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.31 Timer A Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN Input Cycle Time	150		ns
$t_{w(TAH)}$	TAiIN Input HIGH Pulse Width	60		ns
$t_{w(TAL)}$	TAiIN Input LOW Pulse Width	60		ns

Table 5.32 Timer A Input (Gating Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN Input Cycle Time	600		ns
$t_{w(TAH)}$	TAiIN Input HIGH Pulse Width	300		ns
$t_{w(TAL)}$	TAiIN Input LOW Pulse Width	300		ns

Table 5.33 Timer A Input (External Trigger Input in One-shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN Input Cycle Time	300		ns
$t_{w(TAH)}$	TAiIN Input HIGH Pulse Width	150		ns
$t_{w(TAL)}$	TAiIN Input LOW Pulse Width	150		ns

Table 5.34 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN Input HIGH Pulse Width	150		ns
$t_{w(TAL)}$	TAiIN Input LOW Pulse Width	150		ns

Table 5.35 Timer A Input (Counter Increment/Decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(UP)}$	TAiOUT Input Cycle Time	3000		ns
$t_{w(UPH)}$	TAiOUT Input HIGH Pulse Width	1500		ns
$t_{w(UPL)}$	TAiOUT Input LOW Pulse Width	1500		ns
$t_{su(UP-TIN)}$	TAiOUT Input Setup Time	600		ns
$t_{h(TIN-UP)}$	TAiOUT Input Hold Time	600		ns

Table 5.36 Timer A Input (Two-phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN Input Cycle Time	2		µs
$t_{su(TAIN-TAOUT)}$	TAiOUT Input Setup Time	500		ns
$t_{su(TAOUT-TAIN)}$	TAiIN Input Setup Time	500		ns

$V_{CC1}=V_{CC2}=3V$

Timing Requirements

(V_{CC1} = V_{CC2} = 3V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.37 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time (counted on one edge)	150		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width (counted on one edge)	60		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width (counted on one edge)	60		ns
$t_{c(TB)}$	TBiIN Input Cycle Time (counted on both edges)	300		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width (counted on both edges)	120		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width (counted on both edges)	120		ns

Table 5.38 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time	600		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width	300		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width	300		ns

Table 5.39 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time	600		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width	300		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width	300		ns

Table 5.40 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(AD)}$	$\overline{\text{ADTRG}}$ Input Cycle Time	1500		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ Input LOW Pulse Width	200		ns

Table 5.41 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi Input Cycle Time	300		ns
$t_{w(CKH)}$	CLKi Input HIGH Pulse Width	150		ns
$t_{w(CKL)}$	CLKi Input LOW Pulse Width	150		ns
$t_{d(C-Q)}$	TXDi Output Delay Time		160	ns
$t_{h(C-Q)}$	TXDi Hold Time	0		ns
$t_{su(D-C)}$	RXDi Input Setup Time	100		ns
$t_{h(C-D)}$	RXDi Input Hold Time	90		ns

Table 5.42 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ Input HIGH Pulse Width	380		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ Input LOW Pulse Width	380		ns

$V_{CC1}=V_{CC2}=3V$

Switching Characteristics

(V_{CC1} = V_{CC2} = 3V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.43 Memory Expansion and Microprocessor Modes (for setting with no wait)

Symbol	Parameter		Standard		Unit
			Min.	Max.	
td(BCLK-AD)	Address Output Delay Time	See **Figure 5.8**		30	ns
th(BCLK-AD)	Address Output Hold Time (in relation to BCLK)		0		ns
th(RD-AD)	Address Output Hold Time (in relation to RD)		0		ns
th(WR-AD)	Address Output Hold Time (in relation to WR)		(NOTE 2)		ns
td(BCLK-CS)	Chip Select Output Delay Time			30	ns
th(BCLK-CS)	Chip Select Output Hold Time (in relation to BCLK)		0		ns
td(BCLK-ALE)	ALE Signal Output Delay Time			25	ns
th(BCLK-ALE)	ALE Signal Output Hold Time		–4		ns
td(BCLK-RD)	RD Signal Output Delay Time			30	ns
th(BCLK-RD)	RD Signal Output Hold Time		0		ns
td(BCLK-WR)	WR Signal Output Delay Time			30	ns
th(BCLK-WR)	WR Signal Output Hold Time		0		ns
td(BCLK-DB)	Data Output Delay Time (in relation to BCLK)			40	ns
th(BCLK-DB)	Data Output Hold Time (in relation to BCLK) (3)		4		ns
td(DB-WR)	Data Output Delay Time (in relation to WR)		(NOTE 1)		ns
th(WR-DB)	Data Output Hold Time (in relation to WR) (3)		(NOTE 2)		ns
td(BCLK-HLDA)	HLDA Output Delay Time			40	ns

NOTES:

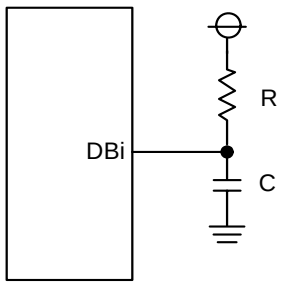
1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times10^{9}}{f(BCLK)} - 40[ns]$$ f(BCLK) is 12.5MHz or less.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times10^{9}}{f(BCLK)} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
   Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
   Hold time of data bus is expressed in
   $t = -CR \times \ln(1 - V_{OL} / V_{CC1})$
   by a circuit of the right figure.
   For example, when V_{OL} = 0.2V_{CC1}, C = 30pF, R = 1kΩ, hold time of output "L" level is
   $t = -30pF \times 1k\Omega \times \ln(1 - 0.2V_{CC1} / V_{CC1})$
   = 6.7ns.



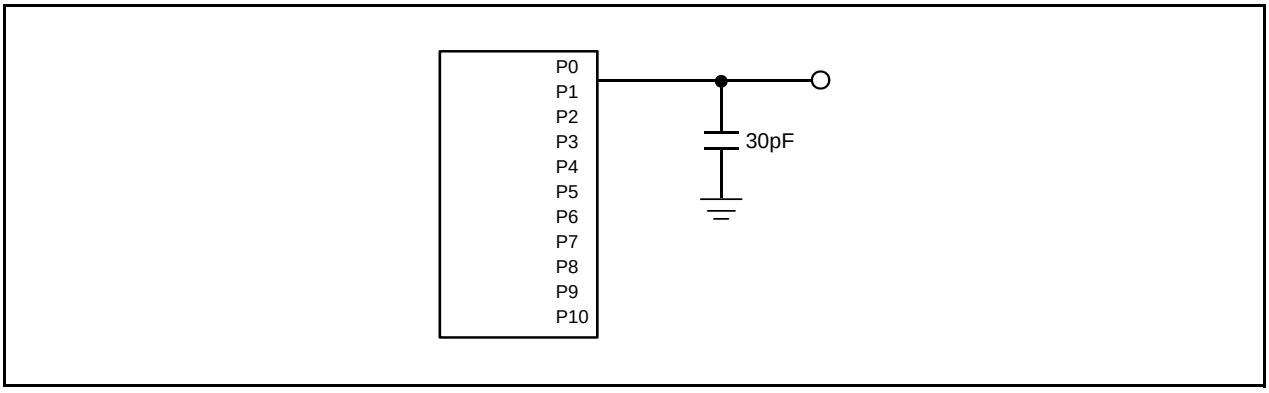


Figure 5.8 Ports P0 to P10 Measurement Circuit

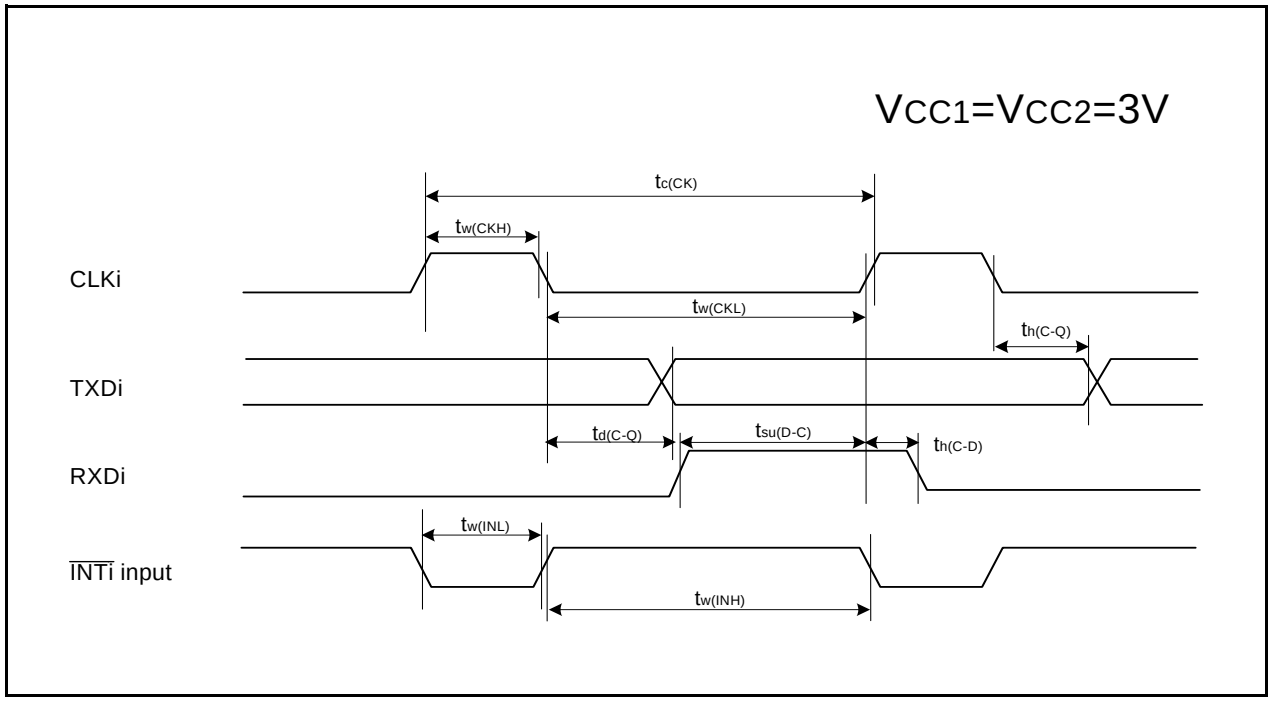
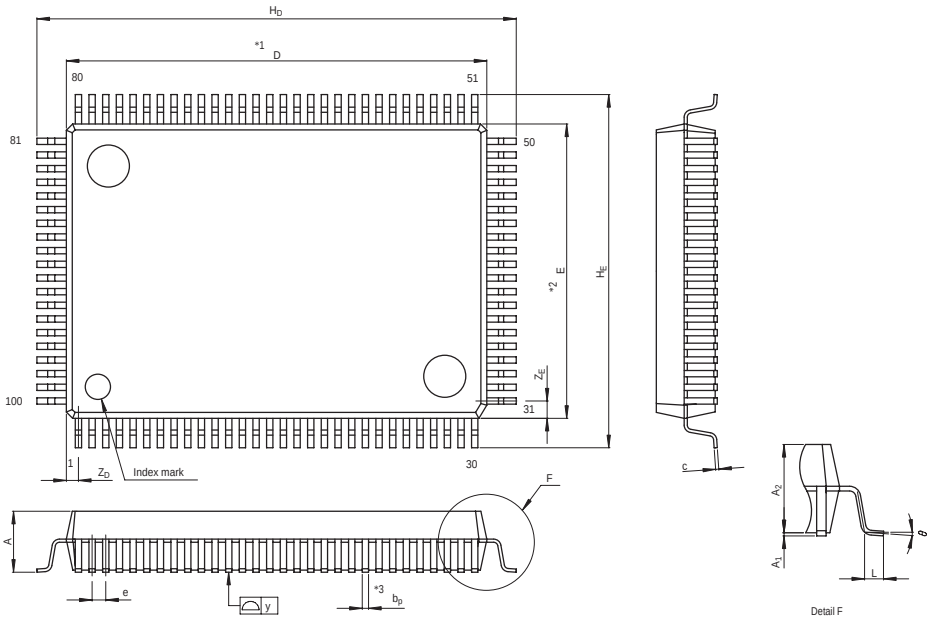


Figure 5.10 Timing Diagram (2)

Appendix 1. Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the "Packages" section of the Renesas Technology website.

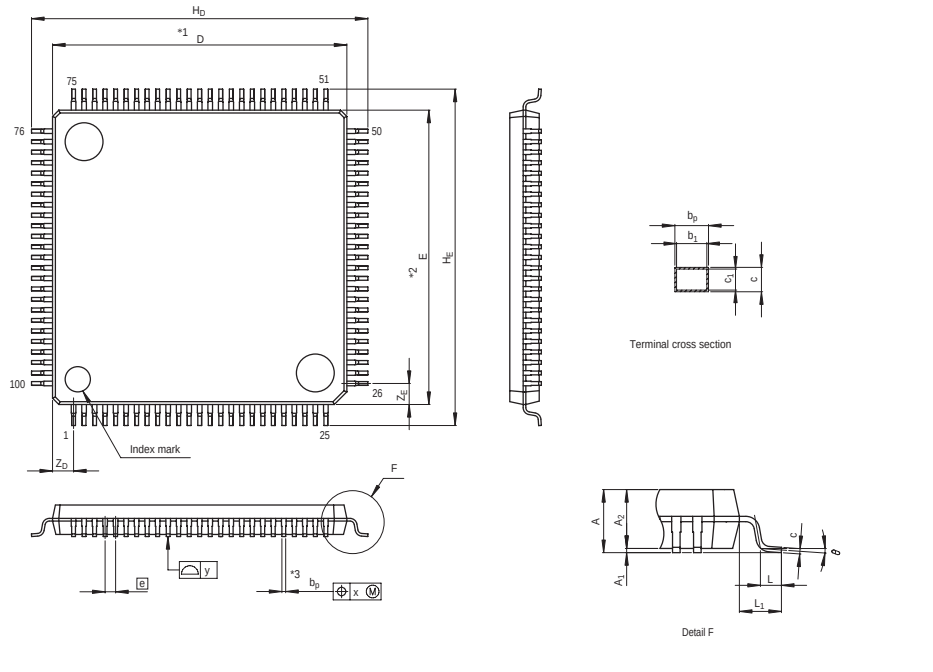
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-QFP100-14x20-0.65	PRQP0100JB-A	100P6S-A	1.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.8	20.0	20.2
E	13.8	14.0	14.2
A_2	—	2.8	—
H_D	22.5	22.8	23.1
H_E	16.5	16.8	17.1
A	—	—	3.05
A_1	0	0.1	0.2
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
e	0.5	0.65	0.8
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.825	—
L	0.4	0.6	0.8

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—